D. Thin Film Process Technology 분과 [TK2-D] Thin Film Process II

| TK2-D-1 10:45~11:15 | [초청] Strategies for Stabilization of Metastable Phases in Atomic Layer Deposition Seong Keun Kim Center for Electronic Materials, KIST |
|------------------------|--|
| TK2-D-2 11:15~11:30 | Hollow Cathode Plasma Source를 이용한 고품질 SiN ALD 공정 Jae Chan Park ¹ , Dae Hyun Kim ² , Tae Jun Seok ¹ , Dae Woong Kim ¹ , Woo-Hee Kim ¹ , and Tae Joo Park ^{1,2} ¹ Department of Materials Science and Chemical Engineering, Hanyang University, ² Department of Advanced Materials Engineering, Hanyang University |
| TK2-D-3 11:30~11:45 | Low-temperature Atomic Layer Deposition of Silicon Nitride Film Using Silicon Halide Precursors 신종우 ¹ , 문찬희 ¹ , 하제영 ¹ , 유능경 ² , 송봉근 ² , 이한보람 ¹ <i>¹ 인천대학교 신소재공학과,² 홍익대학교 화학공학과</i> |
| TK2-D-4 11:45~12:00 | N₂H₄를 이용한 저온 Thermal ALD SiN 박막 공정 Jae Chan Park¹, Dae Hyun Kim², Tae Jun Seok¹, Dae Woong Kim¹, Woo-Hee Kim¹, and Tae Joo Park¹² ¹Department of Materials Science and Chemical Engineering, Hanyang University, ²Department of Materials Science and Chemical Engineering, Hanyang University |
| TK2-D-5 12:00~12:15 | Growth Behavior and Properties of Ru Film by Electric Field/Potential Assisted Atomic Layer Deposition (EA-ALD) Ji won Han and Tae Joo Park Department of Materials Science and Chemical Engineering, Hanyang University |
| TK2-D-6 12:15~12:30 | Improvement in the Surface Morphology of the Bottom Ru Electrode for DRAM Capacitor Dae Seon Kwon, Dong Gun Kim, Junil Lim, Tae Kyun Kim, Haeng Ha Seo, and Cheol Seong Hwang Department of Materials Science and Engineering and Inter-University Semiconductor Research Center, Seoul National University |